

Amendments to the Specification:

Please replace the title beginning at page 1, line 1 with the following amended title:

-- A Hybrid Integrated Circuit Device with High Melting Point Brazing Material --

Please delete the previous abstract at page 22, line 2 and add the following new abstract at page 22, line 2:

-- In order to prevent short-circuiting when a chip component is brazed to pads of a conductive wiring layer, a hybrid semiconductor circuit includes the chip component with terminal electrodes formed at both ends, a first conductive wiring layer on which the pads are provided such that they correspond to the terminal electrodes, and an overcoat resin that covers the first conductive wiring layer excluding the pads. The terminal electrodes of the chip component are adhered to the pads by a conductive adhesive and an insulating adhesive is provided between the pads. --